

4A, 20ns, MOSFET Driver

General Description

The MAX5078A/MAX5078B high-speed MOSFET drivers source and sink up to 4A peak current. These devices feature a fast 20ns propagation delay and 20ns rise and fall times while driving a 5000pF capacitive load. Propagation delay time is minimized and matched between the inverting and noninverting inputs. High sourcing/sinking peak currents, low propagation delay, and thermally enhanced packages make the MAX5078A/MAX5078B ideal for high-frequency and high-power circuits.

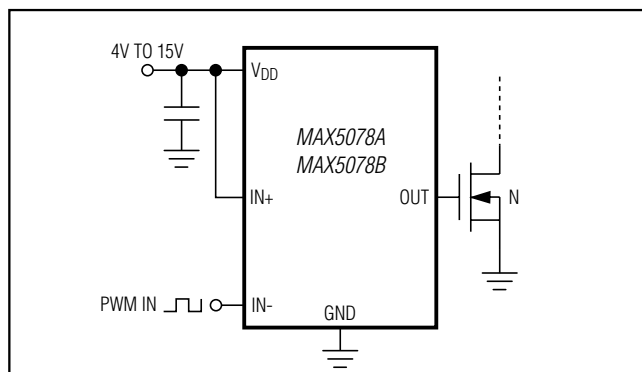
The MAX5078A/MAX5078B operate from a 4V to 15V single power supply and consume 40μA (typ) of supply current when not switching. These devices have an internal logic circuitry that prevents shoot-through during output state changes to minimize the operating current at a high switching frequency. The logic inputs are protected against voltage spikes up to +18V, regardless of the V_{DD} voltage. The MAX5078A has CMOS input logic levels while the MAX5078B has TTL-compatible input logic levels.

The MAX5078A/MAX5078B feature both inverting and noninverting inputs for greater flexibility in controlling the MOSFET. They are available in a 6-pin TDFN (3mm x 3mm) package and operate over the automotive temperature range of -40°C to +125°C.

Applications

Power MOSFET Switching Motor Control
Switch-Mode Power Supplies Power-Supply Modules
DC-DC Converters

Typical Operating Circuit



Features

- ◆ 4V to 15V Single Power Supply
- ◆ 4A Peak Source/Sink Drive Current
- ◆ 20ns (typ) Propagation Delay
- ◆ Matching Delay Between Inverting and Noninverting Inputs
- ◆ V_{DD} / 2 CMOS (MAX5078A)/TTL (MAX5078B) Logic Inputs
- ◆ 0.1 x V_{DD} (CMOS) and 0.3V (TTL) Logic-Input Hysteresis
- ◆ Up to +18V Logic Inputs (Regardless of V_{DD} Voltage)
- ◆ Low Input Capacitance: 2.5pF (typ)
- ◆ 40μA (typ) Quiescent Current
- ◆ -40°C to +125°C Operating Temperature Range
- ◆ 6-Pin TDFN Package

Ordering Information

PART	TEMP RANGE	PIN-PACKAGE
MAX5078AATT+	-40°C to +125°C	6 TDFN-EP*
MAX5078AATT/V+	-40°C to +125°C	6 TDFN-EP*
MAX5078BATT+	-40°C to +125°C	6 TDFN-EP*
MAX5078BATT/V+	-40°C to +125°C	6 TDFN-EP*

*EP = Exposed pad.

+Denotes a lead(Pb)-free/RoHS-compliant package.

*EP = Exposed pad.

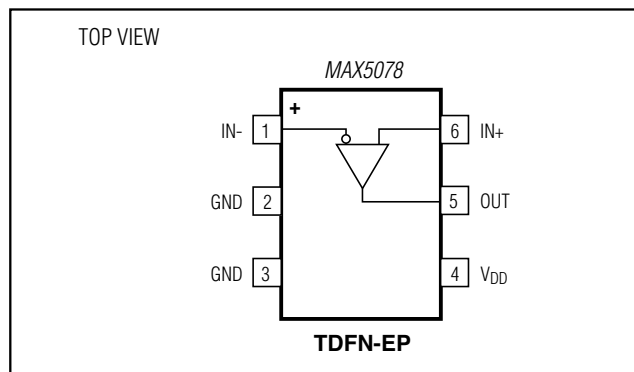
/V denotes an automotive qualified part.

Note: Devices are also available in a tape-and-reel package. Specify tape and reel by adding "T" to the part number when ordering.

Selector Guide

PART	PIN-PACKAGE	LOGIC INPUT
MAX5078AATT	6 TDFN-EP	V _{DD} / 2 CMOS
MAX5078BATT	6 TDFN-EP	TTL

Pin Configuration



For pricing, delivery, and ordering information, please contact Maxim Direct at 1-888-629-4642, or visit Maxim's website at www.maximintegrated.com.

MAX5078

4A, 20ns, MOSFET Driver

ABSOLUTE MAXIMUM RATINGS

(Voltages referenced to GND.)

V_{DD}.....-0.3V to +18V
 IN+, IN--0.3V to +18V
 OUT-0.3V to (V_{DD} + 0.3V)
 OUT Short-Circuit Duration10ms
 Continuous Source/Sink Current at OUT_ (P_D < P_{DMAX})200mA

Continuous Power Dissipation (T_A = +70°C)

6-Pin TDFN-EP (derate 18.2mW/°C above +70°C).....1454mW
 Operating Temperature Range.....-40°C to +125°C
 Storage Temperature Range-65°C to +150°C
 Junction Temperature+150°C
 Lead Temperature (soldering, 10s).....+300°C
 Soldering Temperature (reflow).....+260°C

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

PACKAGE THERMAL CHARACTERISTICS (Note 1)

Junction-to-Ambient Thermal Resistance (θ_{JA}).....42°C/W
 Junction-to-Case Thermal Resistance (θ_{JC}).....9°C/W

Note 1: Package thermal resistances were obtained using the method described in JEDEC specification JESD51-7, using a four-layer board. For detailed information on package thermal considerations, refer to www.maximintegrated.com/thermal-tutorial.

ELECTRICAL CHARACTERISTICS

(V_{DD} = 4V to 15V, T_A = -40°C to +125°C, unless otherwise noted. Typical values are at V_{DD} = 15V and T_A = +25°C.) (Note 1)

PARAMETER	SYMBOL	CONDITIONS		MIN	TYP	MAX	UNITS
POWER SUPPLY							
V _{DD} Operating Range	V _{DD}			4		15	V
V _{DD} Undervoltage Lockout	UVLO	V _{DD} rising		3.00	3.5	3.85	V
V _{DD} Undervoltage Lockout Hysteresis				200			mV
V _{DD} Undervoltage Lockout to Output Delay		V _{DD} rising		12			μs
V _{DD} Supply Current	I _{DD}	V _{IN+} = 0V, I _{N-} = V _{DD} (not switching)	V _{DD} = 4V	28	55	μA	
			V _{DD} = 15V	40	75		
	I _{DD-SW}	Switching at 250kHz, C _L = 0		0.5	1.2	2.2	mA
DRIVER OUTPUT (SINK)							
Driver Output Resistance Pulling Down	R _{ON-N}	V _{DD} = 15V, I _{OUT} = -100mA	T _A = +25°C	1.1	1.8	Ω	
			T _A = +125°C	1.5	2.4		
		V _{DD} = 4.5V, I _{OUT} = -100mA	T _A = +25°C	2.2	3.3		
			T _A = +125°C	3.0	4.5		
Peak Output Current (Sinking)	I _{PK-N}	V _{DD} = 15V, C _L = 10,000pF		4		A	
Output-Voltage Low		I _{OUT} = -100mA	V _{DD} = 4.5V	0.45		V	
			V _{DD} = 15V	0.24			
Latchup Protection	I _{LUP}	Reverse current I _{OUT} (Note 2)		400		mA	
DRIVER OUTPUT (SOURCE)							
Driver Output Resistance Pulling Up	R _{ON-P}	V _{DD} = 15V, I _{OUT} = 100mA	T _A = +25°C	1.5	2.1	Ω	
			T _A = +125°C	1.9	2.75		
		V _{DD} = 4.5V, I _{OUT} = 100mA	T _A = +25°C	2.75	4		
			T _A = +125°C	3.75	5.5		
Peak Output Current (Sourcing)	I _{PK-P}	V _{DD} = 15V, C _L = 10,000pF		4		A	

MAX5078

4A, 20ns, MOSFET Driver

ELECTRICAL CHARACTERISTICS (continued)

($V_{DD} = 4V$ to $15V$, $T_A = -40^{\circ}C$ to $+125^{\circ}C$, unless otherwise noted. Typical values are at $V_{DD} = 15V$ and $T_A = +25^{\circ}C$.) (Note 1)

PARAMETER	SYMBOL	CONDITIONS		MIN	TYP	MAX	UNITS
Output-Voltage High		I _{OUT} = 100mA	V _{DD} = 4.5V	V _{DD} - 0.55			V
			V _{DD} = 15V	V _{DD} - 0.275			
LOGIC INPUT (Note 3)							
Logic 1 Input Voltage	V _{IH}	MAX5078A		0.7 x V _{DD}			V
		MAX5078B (Note 4)		2.1			
Logic 0 Input Voltage	V _{IL}	MAX5078A		0.3 x V _{DD}			V
		MAX5078B		0.8			
Logic-Input Hysteresis	V _{HYS}	MAX5078A		0.1 x V _{DD}			V
		MAX5078B		0.3			
Logic-Input-Current Leakage		V _{IN+} = V _{IN-} = 0V or V _{DD}		-1	+0.1	+1	μA
Input Capacitance	C _{IN}				2.5		pF
SWITCHING CHARACTERISTICS FOR V _{DD} = 15V (Figure 1)							
OUT Rise Time	t _R	C _L = 1000pF		4			ns
		C _L = 5000pF		18			
		C _L = 10,000pF		32			
OUT Fall Time	t _F	C _L = 1000pF		4			ns
		C _L = 5000pF		15			
		C _L = 10,000pF		26			
Turn-On Delay Time	t _{D-ON}	C _L = 10,000pF (Note 2)		10	20	34	ns
Turn-Off Delay Time	t _{D-OFF}	C _L = 10,000pF (Note 2)		10	20	34	ns
SWITCHING CHARACTERISTICS FOR V _{DD} = 4.5V (Figure 1)							
OUT Rise Time	t _R	C _L = 1000pF		7			ns
		C _L = 5000pF		37			
		C _L = 10,000pF		85			
OUT Fall Time	t _F	C _L = 1000pF		7			ns
		C _L = 5000pF		30			
		C _L = 10,000pF		75			
Turn-On Delay Time	t _{D-ON}	C _L = 10,000pF (Note 2)		18	35	70	ns
Turn-Off Delay Time	t _{D-OFF}	C _L = 10,000pF (Note 2)		18	35	70	ns

MAX5078

4A, 20ns, MOSFET Driver

ELECTRICAL CHARACTERISTICS (continued)

($V_{DD} = 4V$ to $15V$, $T_A = -40^\circ C$ to $+125^\circ C$, unless otherwise noted. Typical values are at $V_{DD} = 15V$ and $T_A = +25^\circ C$.) (Note 1)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
MATCHING CHARACTERISTICS						
Mismatch Propagation Delays from Inverting and Noninverting Inputs to Output	Δt_{ON-OFF}	$V_{DD} = 15V$, $C_L = 10,000pF$		2		ns
		$V_{DD} = 4.5V$, $C_L = 10,000pF$		4		

Note 1: All devices are 100% tested at $T_A = +25^\circ C$. Specifications over $-40^\circ C$ to $+125^\circ C$ are guaranteed by design.

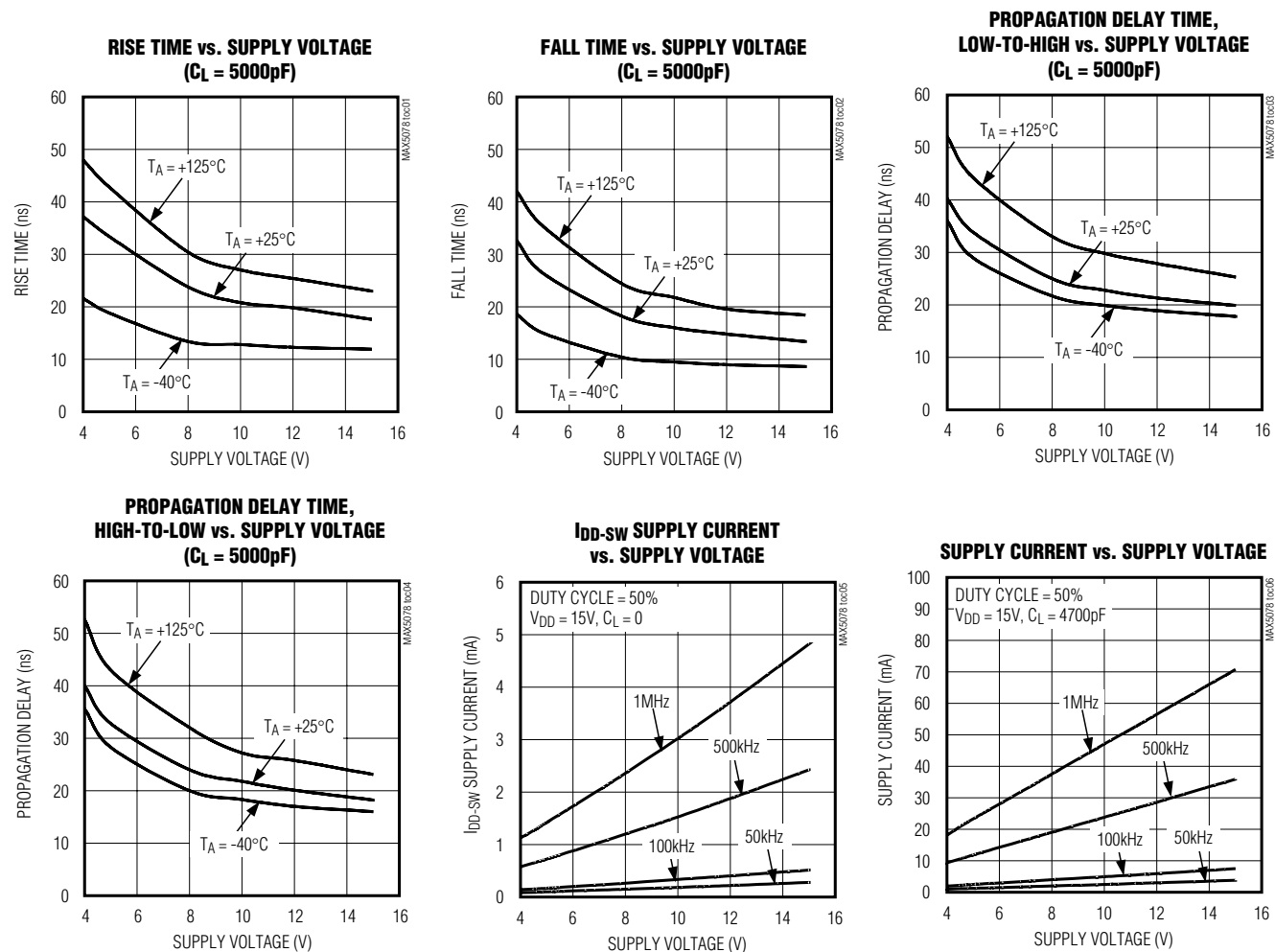
Note 2: Limits are guaranteed by design, not production tested.

Note 3: The logic-input thresholds are tested at $V_{DD} = 4V$ and $V_{DD} = 15V$.

Note 4: TTL compatible with reduced noise immunity.

Typical Operating Characteristics

($T_A = +25^\circ C$, unless otherwise noted.)



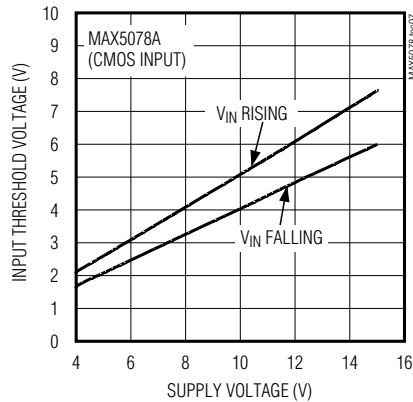
MAX5078

4A, 20ns, MOSFET Driver

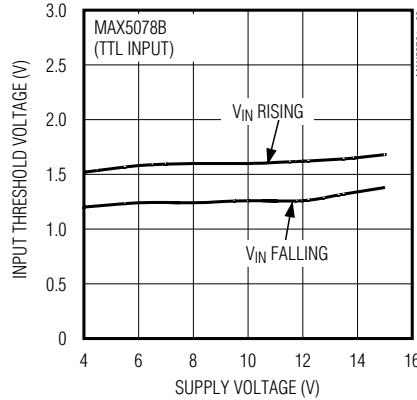
Typical Operating Characteristics (continued)

($T_A = +25^\circ\text{C}$, unless otherwise noted.)

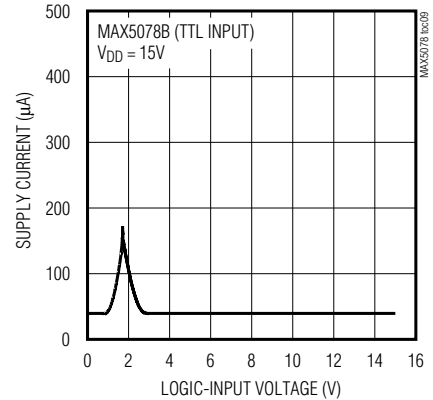
**INPUT THRESHOLD VOLTAGE
vs. SUPPLY VOLTAGE**



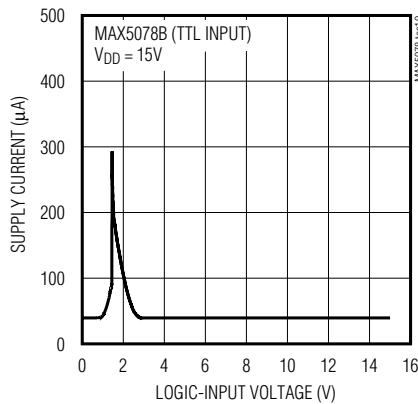
**INPUT THRESHOLD VOLTAGE
vs. SUPPLY VOLTAGE**



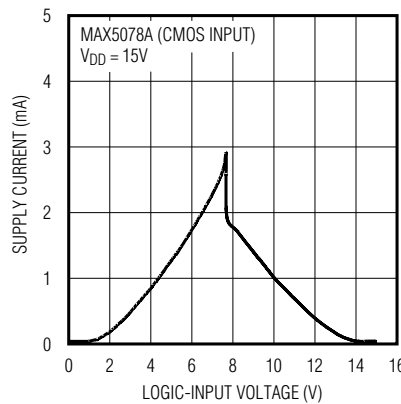
**SUPPLY CURRENT vs. LOGIC-INPUT
VOLTAGE (INPUT LOW-TO-HIGH)**



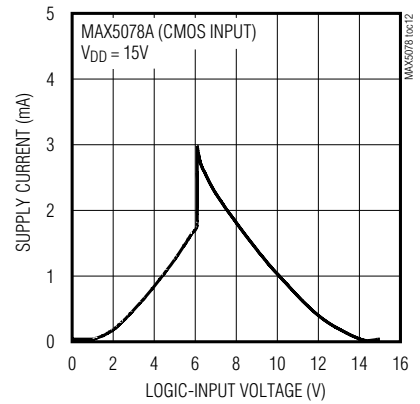
**SUPPLY CURRENT vs. LOGIC-INPUT
VOLTAGE (INPUT HIGH-TO-LOW)**



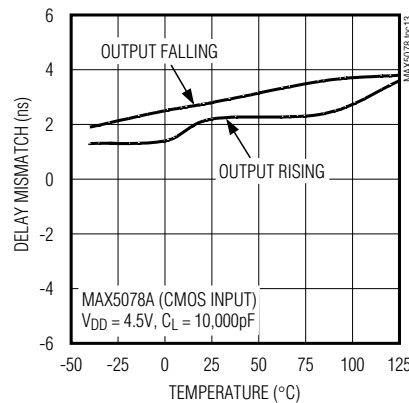
**SUPPLY CURRENT vs. LOGIC-INPUT
VOLTAGE (INPUT LOW-TO-HIGH)**



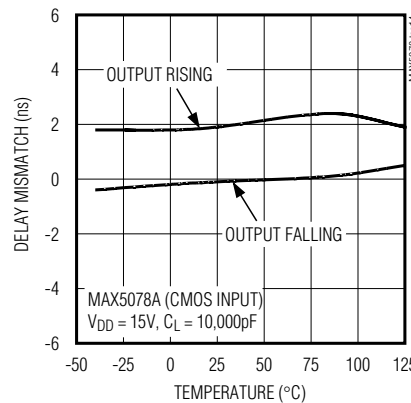
**SUPPLY CURRENT vs. LOGIC-INPUT
VOLTAGE (INPUT HIGH-TO-LOW)**



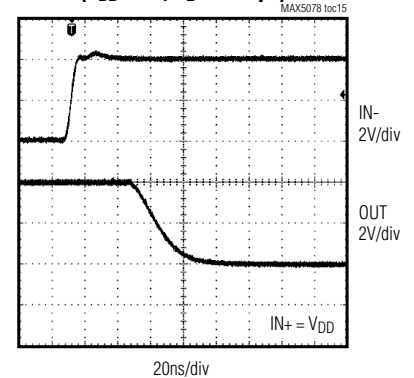
**DELAY MISMATCH BETWEEN IN+
AND IN- TO OUT vs. TEMPERATURE**



**DELAY MISMATCH BETWEEN IN+
AND IN- TO OUT vs. TEMPERATURE**



**LOGIC-INPUT VOLTAGE vs. OUTPUT VOLTAGE
($V_{DD} = 4\text{V}$, $C_L = 5000\text{pF}$)**



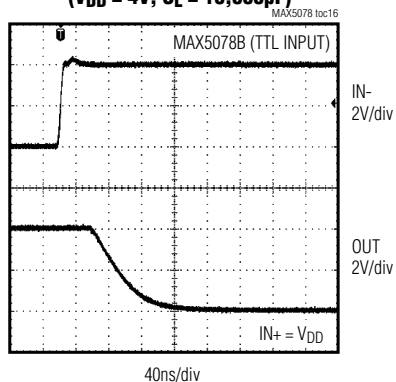
MAX5078

4A, 20ns, MOSFET Driver

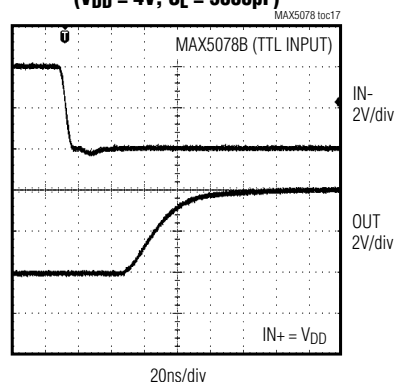
Typical Operating Characteristics (continued)

($T_A = +25^\circ\text{C}$, unless otherwise noted.)

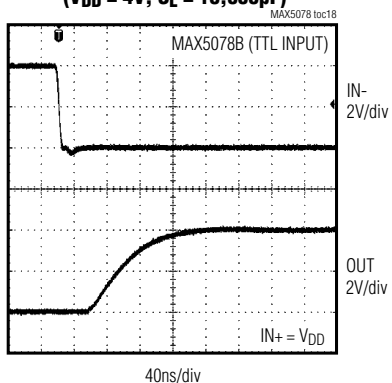
LOGIC-INPUT VOLTAGE vs. OUTPUT VOLTAGE
($V_{DD} = 4\text{V}$, $C_L = 10,000\text{pF}$)



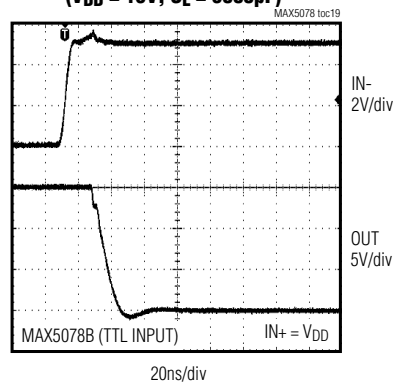
LOGIC-INPUT VOLTAGE vs. OUTPUT VOLTAGE
($V_{DD} = 4\text{V}$, $C_L = 5000\text{pF}$)



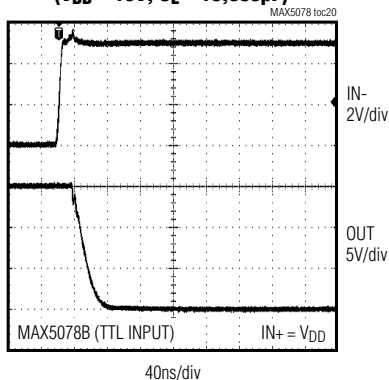
LOGIC-INPUT VOLTAGE vs. OUTPUT VOLTAGE
($V_{DD} = 4\text{V}$, $C_L = 10,000\text{pF}$)



LOGIC-INPUT VOLTAGE vs. OUTPUT VOLTAGE
($V_{DD} = 15\text{V}$, $C_L = 5000\text{pF}$)



LOGIC-INPUT VOLTAGE vs. OUTPUT VOLTAGE
($V_{DD} = 15\text{V}$, $C_L = 10,000\text{pF}$)



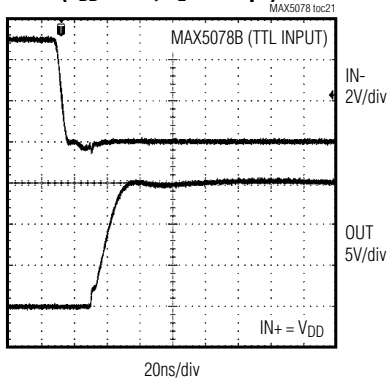
MAX5078

4A, 20ns, MOSFET Driver

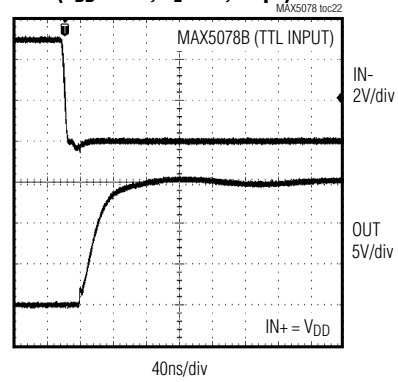
Typical Operating Characteristics (continued)

($T_A = +25^\circ\text{C}$, unless otherwise noted.)

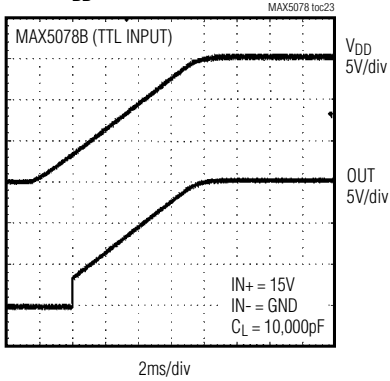
LOGIC-INPUT VOLTAGE vs. OUTPUT VOLTAGE
($V_{DD} = 15\text{V}$, $C_L = 5000\text{pF}$)



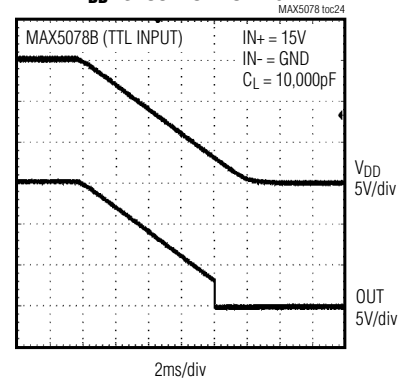
LOGIC-INPUT VOLTAGE vs. OUTPUT VOLTAGE
($V_{DD} = 15\text{V}$, $C_L = 10,000\text{pF}$)



V_{DD} vs. OUTPUT VOLTAGE



V_{DD} vs. OUTPUT VOLTAGE



MAX5078

4A, 20ns, MOSFET Driver

Pin Description

PIN	NAME	FUNCTION
1	IN-	Inverting Logic-Input Terminal. Connect to GND when not used.
2, 3	GND	Ground
4	V _{DD}	Power Supply. Bypass to GND with one or more 0.1µF ceramic capacitors.
5	OUT	Driver Output. Sources or sinks current to turn the external MOSFET on or off.
6	IN+	Noninverting Logic-Input Terminal. Connect to V _{DD} when not used.
—	EP	Exposed Pad. Internally connected to GND. Do not use the exposed pad as the only electrical ground connection.

Detailed Description

V_{DD} Undervoltage Lockout (UVLO)

The MAX5078A/MAX5078B have internal undervoltage lockout (UVLO) for V_{DD}. When V_{DD} is below the UVLO threshold, OUT is pulled low independent of the state of the inputs. The undervoltage lockout is typically 3.5V with 200mV typical hysteresis to avoid chattering. When V_{DD} rises above the UVLO threshold, the output goes high or low depending upon the logic-input levels. Bypass V_{DD} using a low-ESR ceramic capacitor for proper operation (see the *Applications Information* section).

Logic Inputs

The MAX5078A has CMOS logic inputs while the MAX5078B has TTL-compatible logic inputs. The logic inputs are protected against the voltage spikes up to 18V, regardless of the V_{DD} voltage. The TTL and CMOS logic inputs have 300mV and 0.1 × V_{DD} hysteresis, respectively, to avoid double pulsing during transition. The low 2.5pF input capacitance reduces loading and increases switching speed.

The logic inputs are high impedance and must not be left floating. If the inputs are left open, OUT can go to an undefined state as soon as V_{DD} rises above the UVLO threshold. Therefore, the PWM output from the controller must assume proper state when powering up the device.

The MAX5078A/MAX5078B have two logic inputs, providing greater flexibility in controlling the MOSFET. Use IN+ for noninverting logic and IN- for inverting logic operation. Connect IN+ to V_{DD} and IN- to GND, if not used. Alternatively, the unused input can be used as an ON/OFF function. Use IN+ for active-low shutdown logic and IN- for active-high shutdown logic (see Figure 3). See Table 1 for all possible input combinations.

Driver Output

The MAX5078A/MAX5078B have low R_{DS(ON)} p-channel and n-channel devices (totem pole) in the output stage for the fast turn-on/turn-off, high-gate-charge switching MOSFETs. The peak source or sink current is typically 4A. The output voltage (V_{OUT}) is approximately equal to V_{DD} when in high state and is ground when in low state. The driver R_{DS(ON)} is lower at higher V_{DD} resulting in higher source-/sink-current capability and faster switching speeds. The propagation delays from the noninverting and inverting logic inputs to OUT are matched to 2ns typically. The break-before-make logic avoids any cross-conduction between the internal p- and n-channel devices, and eliminates shoot-through, thus reducing the quiescent supply current.

Applications Information

RLC Series Circuit

The driver's R_{DS(ON)} (R_{ON}), internal bond/lead inductance (L_P), trace inductance (L_S), gate inductance (L_G), and gate capacitance (C_G) form a series RLC circuit with a second-order characteristic equation. The series RLC circuit has an undamped natural frequency (ω₀) and a damping ratio (ζ) where:

$$\omega_0 = \frac{1}{\sqrt{(L_P + L_S + L_G) \times C_G}}$$

$$\xi = \frac{R_{ON}}{2 \times \sqrt{\frac{(L_P + L_S + L_G)}{C_G}}}$$

The damping ratio needs to be greater than 0.5 (ideally 1) to avoid ringing. Add a small resistor (R_{GATE}) in series with the gate when driving a very low gate-charge MOSFET, or when the driver is placed away from the MOSFET.

MAX5078

4A, 20ns, MOSFET Driver

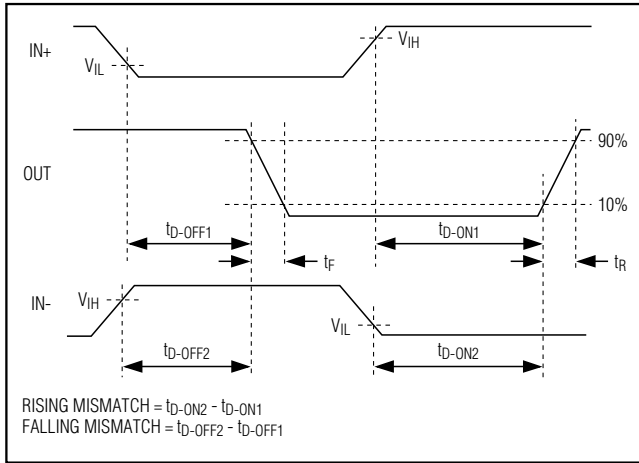


Figure 1. Timing Diagram

Use the following equation to calculate the series resistor:

$$R_{\text{GATE}} \geq \frac{(L_P + L_S + L_G)}{C_G} - R_{\text{ON}}$$

L_P can be approximated as 2nH for the TDFN package. L_S is on the order of 20nH/in. Verify L_G with the MOSFET vendor.

Supply Bypassing and Grounding

Pay extra attention to bypassing and grounding the MAX5078A/MAX5078B. Peak supply and output currents may exceed 4A when driving large external capacitive loads. Supply voltage drops and ground shifts create negative feedback for inverters and may degrade the delay and transition times. Ground shifts due to poor device grounding may also disturb other circuits sharing the same AC ground return path. Any series inductance in the V_{DD} , OUT, and/or GND paths can cause oscillations due to the very high di/dt when switching the MAX5078A/MAX5078B with any capacitive load. Place one or more 0.1μF ceramic capacitors in parallel as close to the device as possible to bypass V_{DD} to GND. Use a ground plane to minimize ground return resistance and series inductance. Place the external MOSFET as close as possible to the MAX5078A/MAX5078B to further minimize board inductance and AC path impedance.

Power Dissipation

Power dissipation of the MAX5078A/MAX5078B consists of three components: caused by the quiescent current, capacitive charge/discharge of internal nodes, and the output current (either capacitive or resistive load). Maintain the sum of these components below the maximum power dissipation limit.

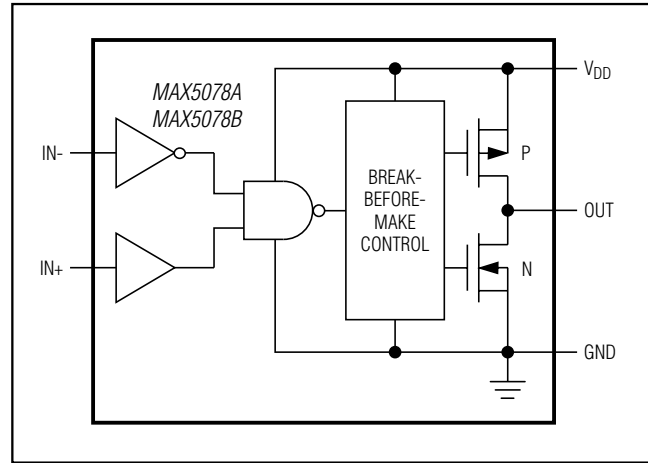


Figure 2. MAX5054 Simplified Diagram (1 Driver)

The current required to charge and discharge the internal nodes is frequency dependent (see the I_{DD-SW} Supply Current vs. Supply Voltage graph in the *Typical Operating Characteristics*). The power dissipation (P_Q) due to the quiescent switching supply current (I_{DD-SW}) can be calculated as:

$$P_Q = V_{DD} \times I_{DD-SW}$$

For capacitive loads, use the following equation to estimate the power dissipation:

$$P_{CLOAD} = C_{LOAD} \times (V_{DD})^2 \times f_{SW}$$

where C_{LOAD} is the capacitive load, V_{DD} is the supply voltage, and f_{SW} is the switching frequency.

Calculate the total power dissipation (P_T) as follows:

$$P_T = P_Q + P_{CLOAD}$$

Use the following equations to estimate the MAX5078A/MA5078B total power dissipation when driving a ground-referenced resistive load:

$$P_T = P_Q + P_{RLOAD}$$

$$P_{RLOAD} = D \times R_{ON(MAX)} \times I_{LOAD}^2$$

where D is the fraction of the period the MAX5078A/MA5078B's output pulls high, $R_{ON(MAX)}$ is the maximum on-resistance of the device with the output high, and I_{LOAD} is the output load current of the MAX5078A/MAX5078B.

Layout Information

The MAX5078A/MAX5078B MOSFET drivers source and sink large currents to create very fast rising and falling edges at the gate of the switching MOSFET. The high di/dt can cause unacceptable ringing if the trace lengths and impedances are not well controlled.

MAX5078

4A, 20ns, MOSFET Driver

Table 1. MAX5078 Truth Table

IN+	IN-	OUT
Low	Low	Low
Low	High	Low
High	Low	High
High	High	Low

Use the following PC board layout guidelines when designing with the MAX5078A/MAX5078B:

- Place one or more 0.1μF decoupling ceramic capacitors from V_{DD} to GND as close to the device as possible. Connect V_{DD} and GND to large copper areas. Place one bulk capacitor of 10μF (min) on the PC board with a low resistance path to the V_{DD} input and GND of the MAX5078A/MAX5078B.
- Two AC current loops form between the device and the gate of the driven MOSFET. The MOSFET looks like a large capacitance from gate to source when the gate pulls low. The active current loop is from the MOSFET gate to OUT of the MAX5078A/MAX5078B, to GND of the MAX5078A/MAX5078B, and to the source of the MOSFET. When the gate of the MOSFET pulls high, the active current is from the V_{DD} terminal of the decoupling capacitor, to V_{DD} of the MAX5078A/MAX5078B, to OUT of the MAX5078A/MAX5078B, to the MOSFET gate, to the MOSFET source, and to the negative terminal of the decoupling capacitor. Both charging current and discharging current loops are important. Minimize the physical distance and the impedance in these AC current paths.
- Keep the device as close to the MOSFET as possible.
- In a multilayer PC board, the inner layers should consist of a GND plane containing the discharging and charging current loops.
- Pay extra attention to the ground loop and use a low-impedance source when using a TTL logic-input device. Fast fall time at OUT may corrupt the input during transition.

Exposed Pad

The TDFN-EP package has an exposed pad on the bottom of its package. This pad is internally connected to GND. For the best thermal conductivity, solder the exposed pad to the ground plane in order to dissipate 1.9W. Do not use the ground-connected pad as the only electrical ground connection or ground return. Use GND (pins 2 and 3) as the primary electrical ground connection.

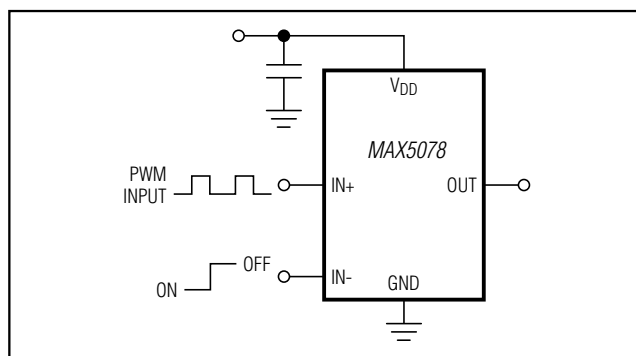


Figure 3. Unused Input as an ON/OFF Function

Additional Application Circuits

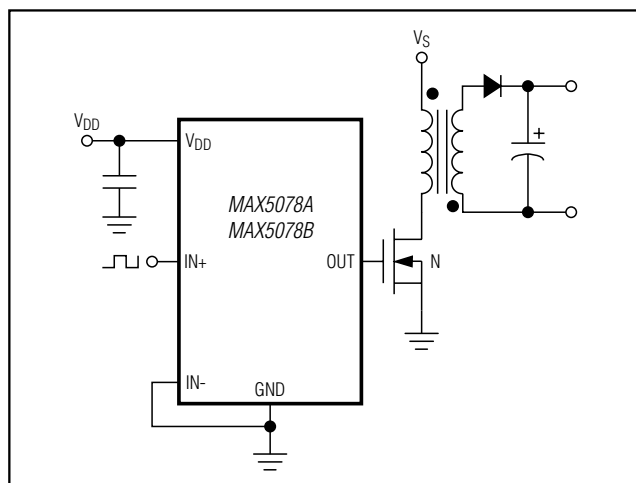


Figure 4. Noninverting Application

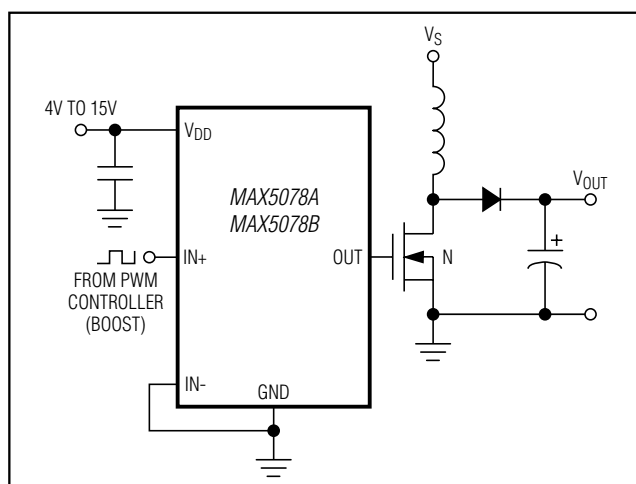


Figure 5. Boost Converter

4A, 20ns, MOSFET Driver

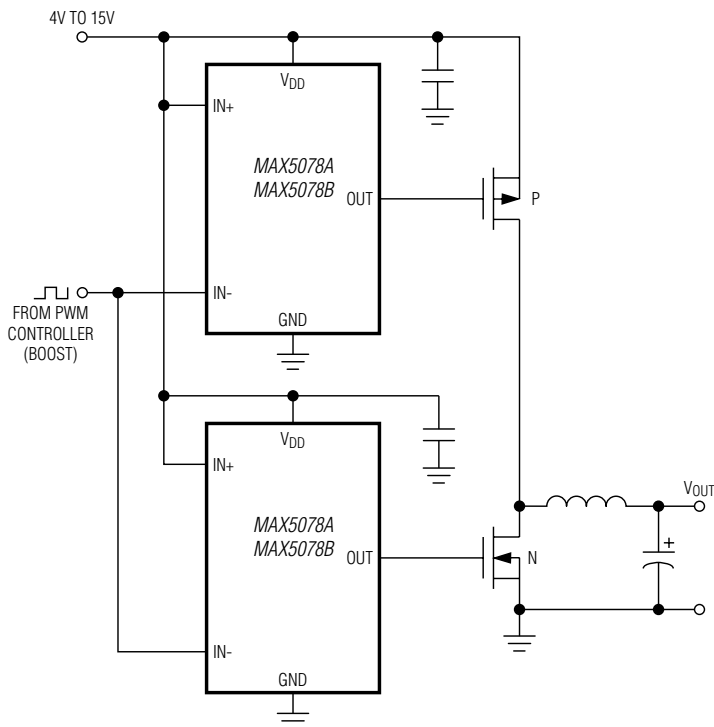


Figure 6. MAX5078A/MAX5078B In High-Power Synchronous Buck Converter

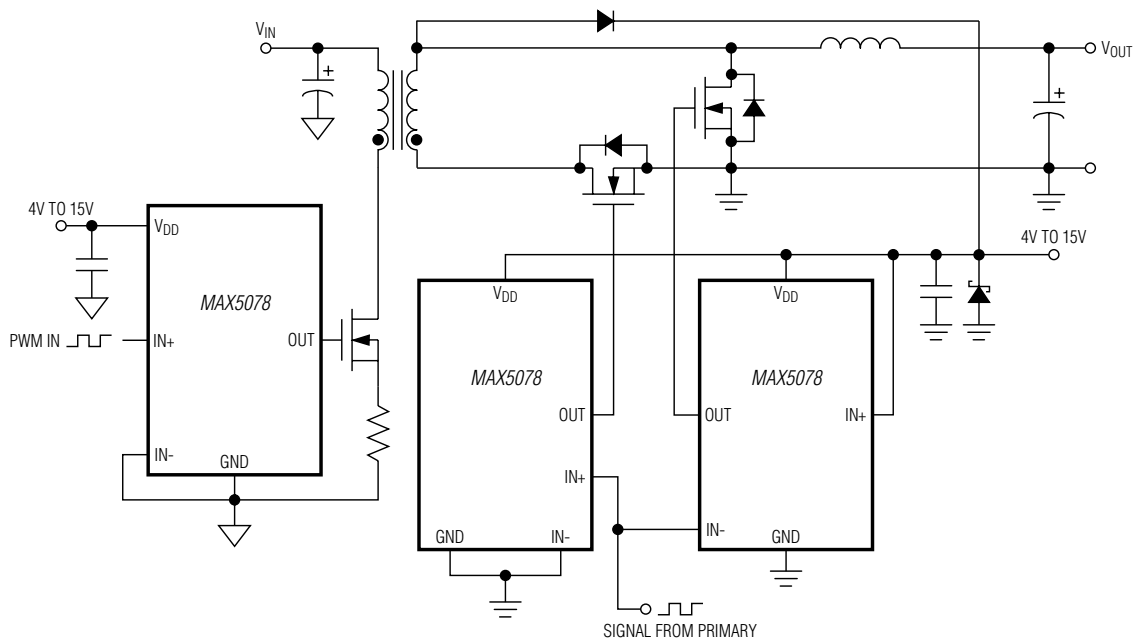


Figure 7. Forward Converter with Secondary-Side Synchronous Rectification

MAX5078

4A, 20ns, MOSFET Driver

Chip Information

PROCESS: CMOS

Package Information

For the latest package outline information and land patterns (footprints), go to www.maximintegrated.com/packages. Note that a "+", "#", or "-" in the package code indicates RoHS status only. Package drawings may show a different suffix character, but the drawing pertains to the package regardless of RoHS status.

PACKAGE TYPE	PACKAGE CODE	OUTLINE NO.	LAND PATTERN NO.
6 TDFN-EP	T633+2	21-0137	90-0058

MAX5078

4A, 20ns, MOSFET Driver

Revision History

REVISION NUMBER	REVISION DATE	DESCRIPTION	PAGES CHANGED
2	9/12	Added automotive qualified parts to <i>Ordering Information</i>	1



Maxim cannot assume responsibility for use of any circuitry other than circuitry entirely embodied in a Maxim product. No circuit patent licenses are implied. Maxim reserves the right to change the circuitry and specifications without notice at any time. The parametric values (min and max limits) shown in the Electrical Characteristics table are guaranteed. Other parametric values quoted in this data sheet are provided for guidance.

Maxim Integrated 160 Rio Robles, San Jose, CA 95134 USA 1-408-601-1000

13

© 2012 Maxim Integrated Products, Inc. The Maxim logo and Maxim Integrated are trademarks of Maxim Integrated Products, Inc.

Компания «Life Electronics» занимается поставками электронных компонентов импортного и отечественного производства от производителей и со складов крупных дистрибьюторов Европы, Америки и Азии.

С конца 2013 года компания активно расширяет линейку поставок компонентов по направлению коаксиальный кабель, кварцевые генераторы и конденсаторы (керамические, пленочные, электролитические), за счёт заключения дистрибьюторских договоров

Мы предлагаем:

- Конкурентоспособные цены и скидки постоянным клиентам.
- Специальные условия для постоянных клиентов.
- Подбор аналогов.
- Поставку компонентов в любых объемах, удовлетворяющих вашим потребностям.
- Приемлемые сроки поставки, возможна ускоренная поставка.
- Доставку товара в любую точку России и стран СНГ.
- Комплексную поставку.
- Работу по проектам и поставку образцов.
- Формирование склада под заказчика.
- Сертификаты соответствия на поставляемую продукцию (по желанию клиента).
- Тестирование поставляемой продукции.
- Поставку компонентов, требующих военную и космическую приемку.
- Входной контроль качества.
- Наличие сертификата ISO.

В составе нашей компании организован Конструкторский отдел, призванный помогать разработчикам, и инженерам.

Конструкторский отдел помогает осуществить:

- Регистрацию проекта у производителя компонентов.
- Техническую поддержку проекта.
- Защиту от снятия компонента с производства.
- Оценку стоимости проекта по компонентам.
- Изготовление тестовой платы монтаж и пусконаладочные работы.



Тел: +7 (812) 336 43 04 (многоканальный)

Email: org@lifeelectronics.ru

www.lifeelectronics.ru